



<b>Title of Change:</b>	NCV7321 Datasheet update – Revision 12		
<b>Effective date:</b>	21 July 2015		
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Roman.Buzas@onsemi.com>		
<b>Type of notification:</b>	ON Semiconductor will consider this change accepted.		
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other _____		
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input checked="" type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s)		
<b>Description and Purpose: detailed description of the change and reason for the change.</b>			
<p><b>Page 1: Quality statement updated</b></p> <ul style="list-style-type: none"> <li>• NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.</li> <li>• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant</li> </ul> <p><b>Page 1: Features list updated</b></p> <ul style="list-style-type: none"> <li>• LIN Transceiver Supports K-Line Bus Architecture</li> <li>• LIN Compliant to latest LIN Physical Layer Specification Revision 2.x</li> </ul> <p><b>New device derivative introduction</b></p> <ul style="list-style-type: none"> <li>• NCV7321-2 ESD Improved Stand-alone LIN Transceiver <ul style="list-style-type: none"> <li>- NCV7321D12R2G - SOIC-8 package</li> <li>- NCV7321MW2R2G - DFN8 package</li> </ul> </li> <li>• DFN8 package info added (CASE 506BW, package drawing, marking, pinout, pin description, package dimensions, thermal characteristics)</li> <li>• Table 4: Absolute Maximum Ratings update (Improved ESD ratings for new device derivative)</li> </ul>			
<b>List of affected Standard Parts:</b>			
NCV7321D10G NCV7321D10R2G NCV7321D11G NCV7321D11R2G NCV7321D12R2G NCV7321MW2R2G			